

碳化硅肖特基二极管

Silicon Carbide Schottky Diode

KS10120-C

$V_{RRM}$	=	1200 V
$I_F$ ( $T_c=163^{\circ}\text{C}$ )	=	10 A
$Q_c$	=	71 nC

## 特点 / Features

- 肖特基整流器 / 1200-Volt Schottky Rectifier
- 零反向恢复电流 / Zero Reverse Recovery Current
- 零正向恢复电压 / Zero Forward Recovery Voltage
- 高工作频率 / High-Frequency Operation
- 不受温度影响的开关特性 / Temperature-Independent Switching Behavior
- 高速开关 / Extremely Fast Switching
- $V_F$  正温度特性 / Positive Temperature Coefficient on  $V_F$

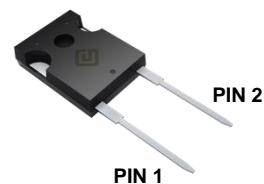
## 优势 / Benefits

- 单极器件 / Replace Bipolar with Unipolar Rectifiers
- 零开关损耗 / Essentially No Switching Losses
- 高效率 / Higher Efficiency
- 减小散热器 / Reduction of Heat Sink Requirements
- 易于并联使用 / Ease of Parallelizing

## 应用领域 / Applications

- 工业电源, 不间断电源 / Industrial Power Supplies, Industrial UPS
- 光伏系统 / Solar system
- 充电桩 / Charging pile
- 电焊机 / Electric welding machine

## 封装 / Package



TO-247-2L



Part Number	Package	Marking
KS10120-C	TO-247-2L	KS10120C

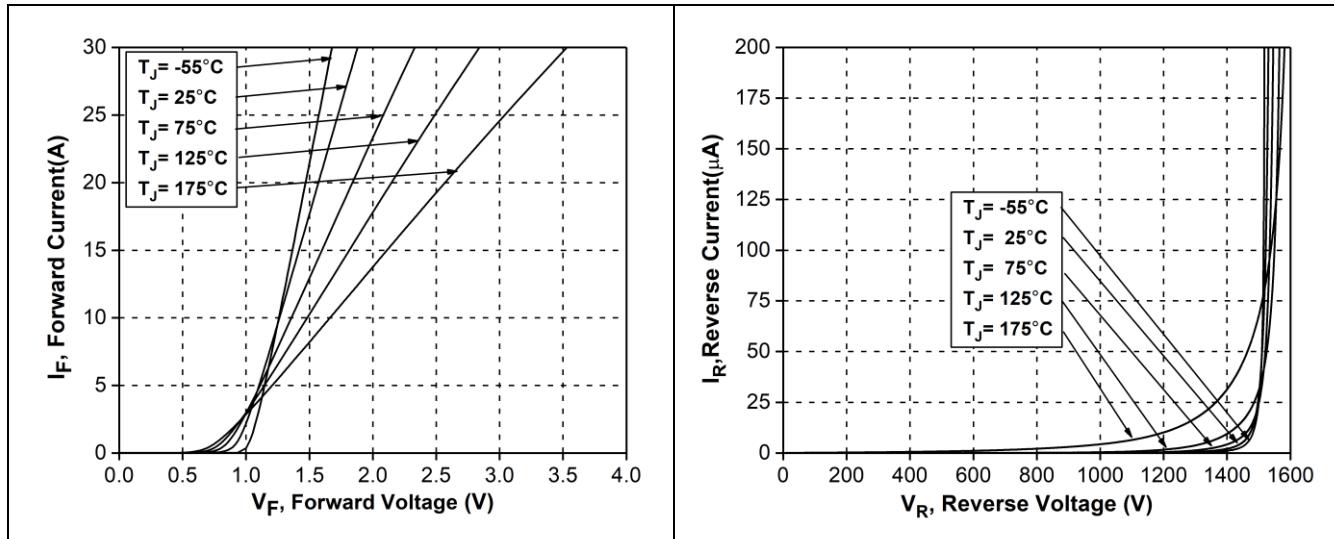
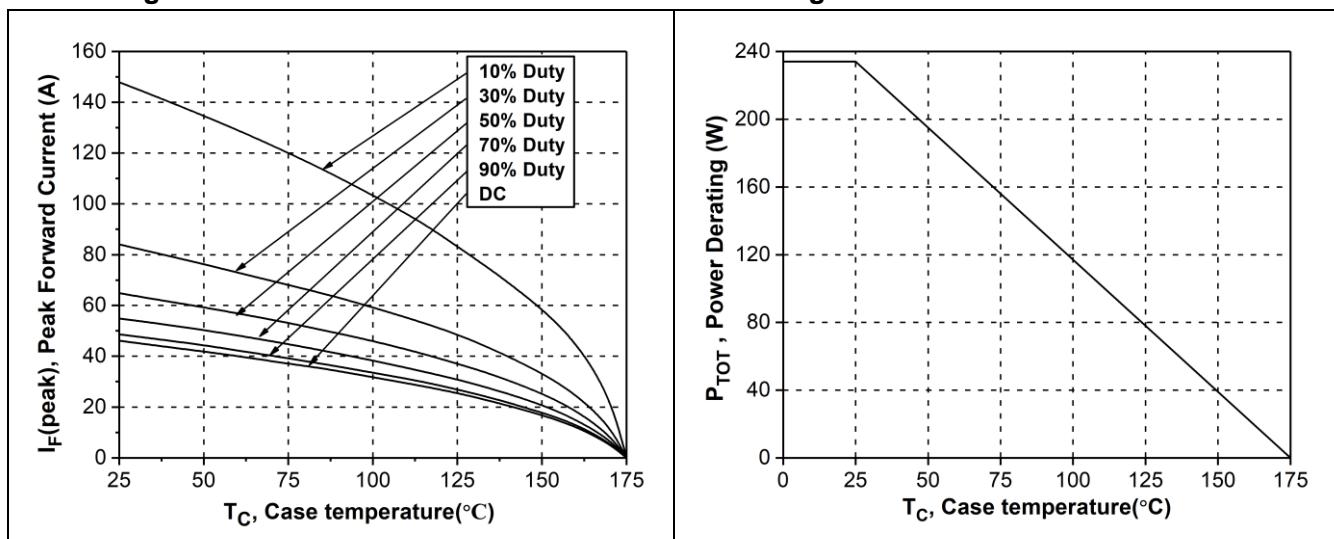
**最大额定值 / Maximum Rated Values (T<sub>c</sub>=25°C unless otherwise specified)**

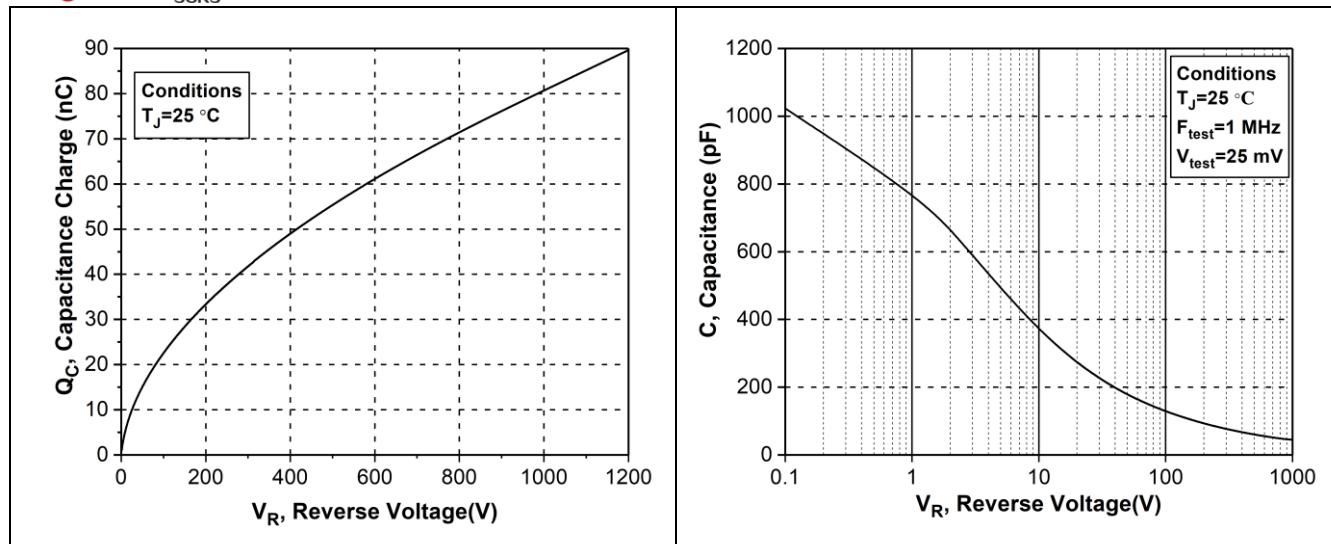
符号 Symbol	参数 Parameter	值 Value	单位 Unit	测试条件 Test Conditions	备注 Note
V <sub>RRM</sub>	反向重复峰值电压 Repetitive peak reverse voltage	1200	V		
V <sub>R</sub>	直流反向阻断电压 DC Peak Reverse Voltage	1200	V		
I <sub>F</sub>	正向电流 Continuous Forward Current	46	A	T <sub>c</sub> =25°C	Figure 3
		23		T <sub>c</sub> =135°C	
		10		T <sub>c</sub> =163°C	
I <sub>FRM</sub>	正向重复峰值电流 Repetitive Peak Forward Surge Current	80	A	T <sub>c</sub> =25°C, t <sub>p</sub> =10ms, Half Sine Pulse	
		66		T <sub>c</sub> =110°C, t <sub>p</sub> =10ms, Half Sine Pulse	
I <sub>FSM</sub>	正向浪涌电流 Non-Repetitive Forward Surge Current	96	A	T <sub>c</sub> =25°C, t <sub>p</sub> =10ms, Half Sine Pulse	Figure 9
		84		T <sub>c</sub> =110°C, t <sub>p</sub> =10ms, Half Sine Pulse	
I <sub>F,MAX</sub>	非重复正向峰值电流 Non-Repetitive Peak Forward Current	865	A	T <sub>c</sub> =25°C, t <sub>p</sub> =10μs, Square Wave Pulse	Figure 9
		795		T <sub>c</sub> =110°C, t <sub>p</sub> =10μs, Square Wave Pulse	
P <sub>tot</sub>	耗散功率 Power Dissipation	234	W	T <sub>c</sub> =25°C	Figure 4
		102		T <sub>c</sub> =110°C	
T <sub>J</sub>	工作结温 Operating Temperature	-55 to +175	°C		
T <sub>stg</sub>	储存温度 Storage Temperature	-55 to +175	°C		

**电气参数 / Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)**

符号 Symbol	参数 Parameter	值 / Value			单位 Unit	测试条件 Test Conditions	备注 Note
		Min.	Typ.	Max.			
V <sub>DC</sub>	击穿电压 DC blocking voltage	1200			V	I <sub>R</sub> =200μA	
V <sub>F</sub>	正向电压 Forward Voltage		1.3 1.8	1.6 2.4	V	I <sub>F</sub> =10A, T <sub>J</sub> =25°C I <sub>F</sub> =10A, T <sub>J</sub> =175°C	Figure 1
			1 10	200 280		V <sub>R</sub> =1200V, T <sub>J</sub> =25°C V <sub>R</sub> =1200V, T <sub>J</sub> =175°C	
Q <sub>C</sub>	容性电荷 Total Capacitive Charge		71		nC	V <sub>R</sub> =800V, T <sub>J</sub> =25°C	Figure 5
C	总电容 Total Capacitance		1023 67 48		pF	V <sub>R</sub> =0V, T <sub>J</sub> =25°C, f=1MHz V <sub>R</sub> =400V, T <sub>J</sub> =25°C, f=1MHz V <sub>R</sub> =800V, T <sub>J</sub> =25°C, f=1MHz	Figure 6
			20		μJ	V <sub>R</sub> =800 V	
E <sub>C</sub>	电容存储能量 Capacitance Stored Energy						Figure 7

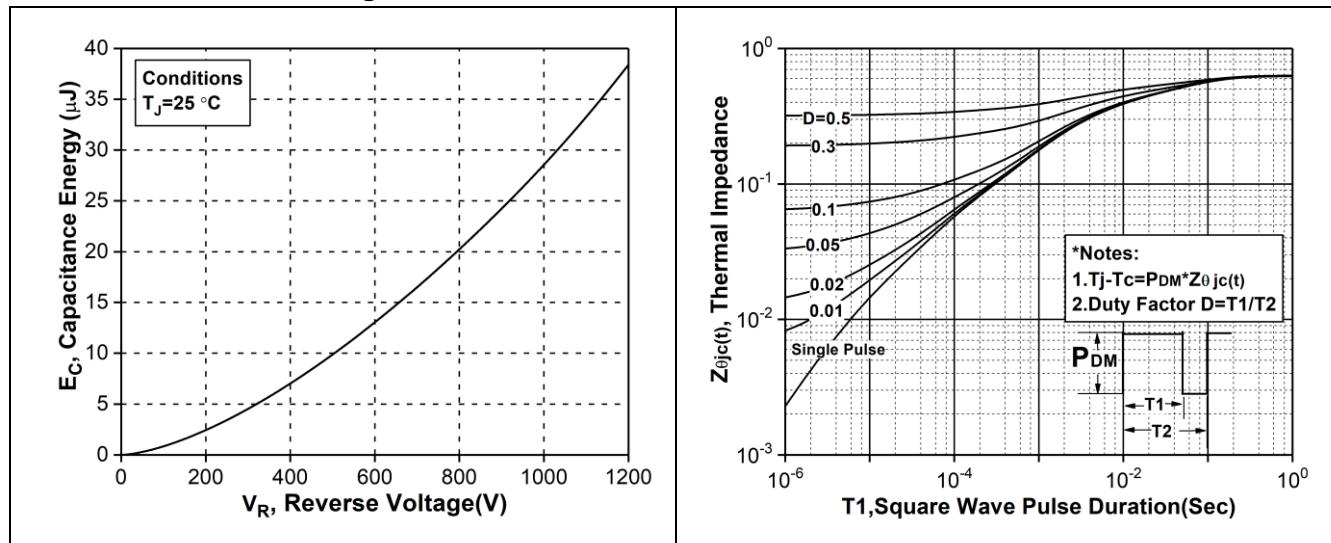
符号 Symbol	参数 Parameter	值 Value	单位 Unit	备注 Note
$R_{eJC}$	结壳热阻 Thermal Resistance(Junction to Case)	0.64	°C/W	Figure 8

**特性曲线 / Typical Performance**

**Figure 1. Forward Characteristics**
**Figure 2. Reverse Characteristics**

**Figure 3. Current Derating**
**Figure 4. Power Derating**



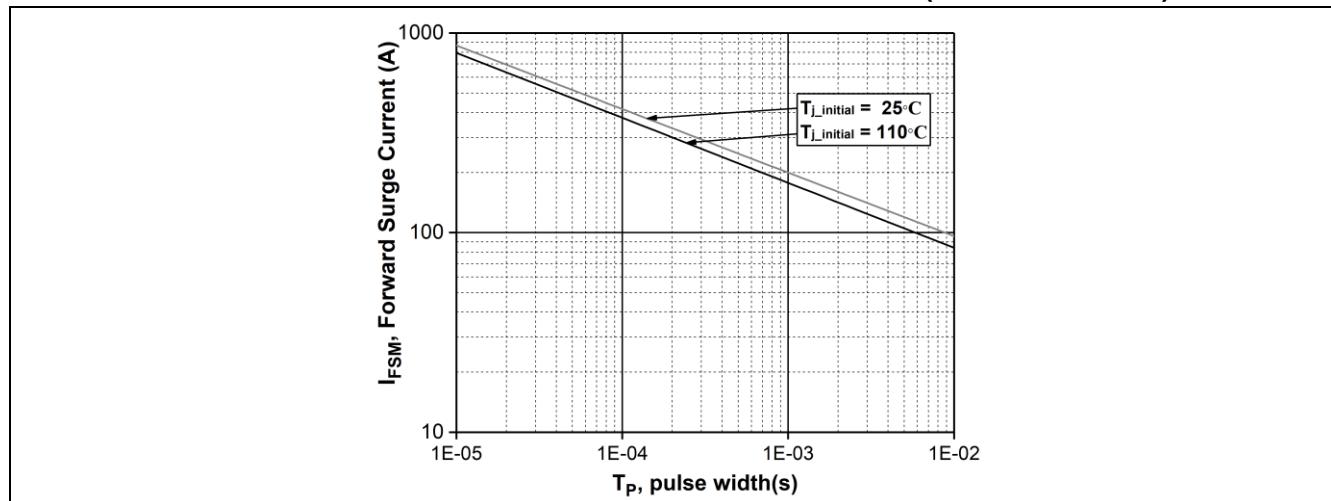
**Figure 5. Capacitance Charge Vs. Reverse Voltage**

**Figure 6. Capacitance Vs. Reverse Voltage**



**Figure 7. Capacitance Stored Energy**

**Figure 8. Transient Thermal Response Curve(Junction-to-Case)**

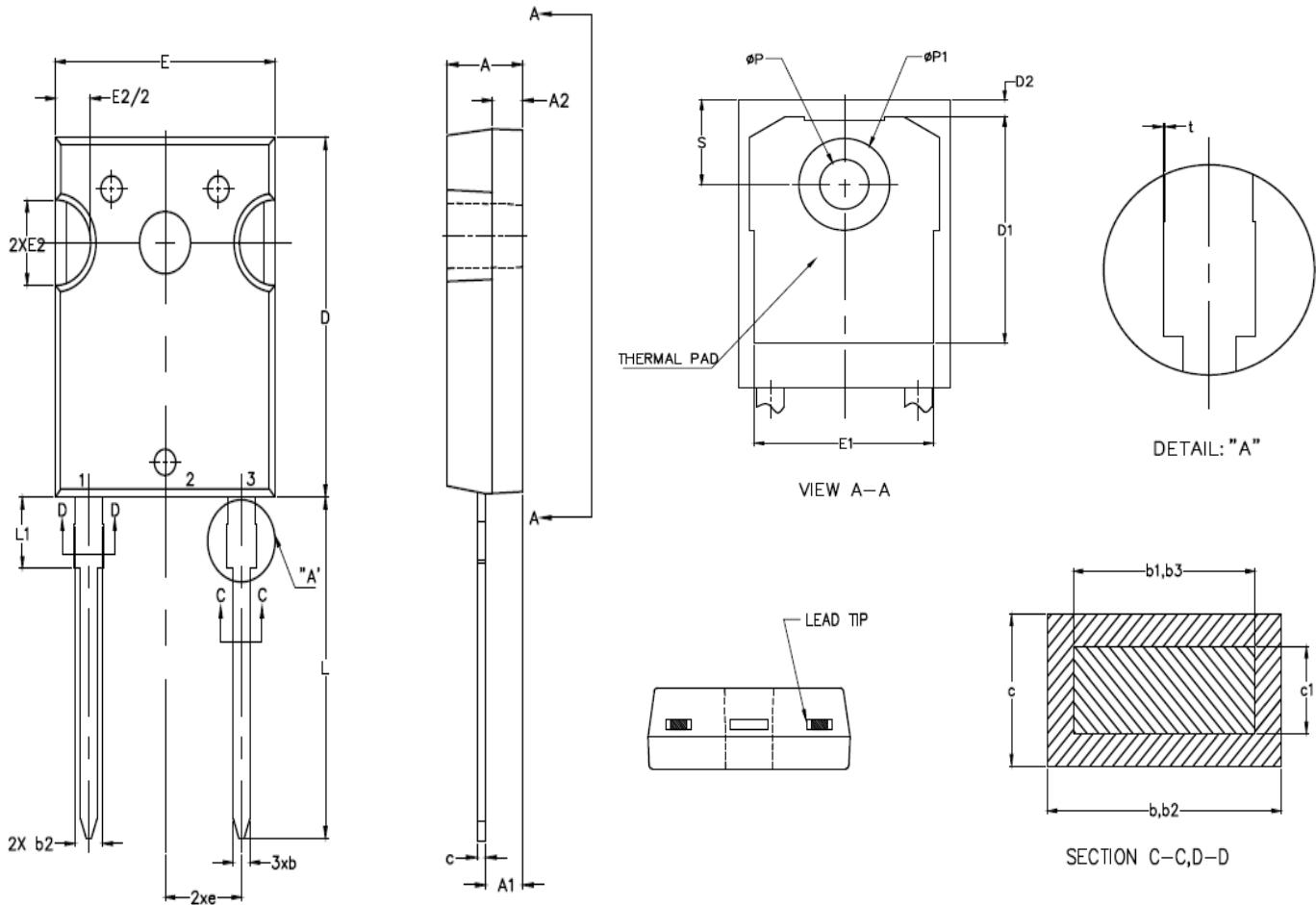


**Figure 9. Non-repetitive peak forward surge current versus pulse duration (sinusoidal waveform)**



## 封装尺寸 / Package Dimensions

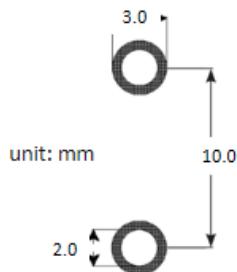
## **Package TO-247-2L (Units: mm)**



SYMBOLS	DIMENSIONS				SYMBOLS	DIMENSIONS				
	mm		inch			mm		inch		
	MIN.	MAX.	MIN.	MAX.		MIN.	MAX.	MIN.	MAX.	
A	4.90	5.10	0.193	0.201	D2	1.05	1.35	0.041	0.053	
A1	2.31	2.51	0.091	0.099	E	15.75	15.90	0.620	0.626	
A2	1.90	2.10	0.075	0.083	E1	13.26	--	0.552	--	
b	1.16	1.26	0.046	0.050	E2	4.90	5.10	0.193	0.201	
b1	1.15	1.22	0.045	0.048	e	5.44BSC		0.214BSC		
b2	1.96	2.06	0.077	0.081	L	19.80	20.10	0.780	0.791	
b3	1.95	2.02	0.077	0.080	L1	--	4.30	--	0.169	
c	0.59	0.66	0.023	0.026	ØP	3.50	3.70	0.138	0.146	
c1	0.58	0.62	0.023	0.024	ØP1	--	7.40	--	0.291	
D	20.90	21.10	0.823	0.831	S	6.05	6.25	0.238	0.246	
D1	16.25	16.85	0.640	0.663	t	0.00	0.15	0.000	0.006	



## 参考焊盘图 / Recommended Solder Pad Layout



TO-247-2L

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